## DATA SHEET

PCA8550
4-bit multiplexed/1-bit latched 5-bit
${ }^{2}{ }^{2} \mathrm{C}$ EEPROM DIP switch

Product data
Supersedes data of 2001 Jan 12

## 4-bit multiplexed/1-bit latched 5-bit ${ }^{2}{ }^{2} \mathrm{C}$ EEPROM DIP switch

## FEATURES

- 4-bit 2-to-1 multiplexer, 1-bit latch DIP switch
- 5-bit internal non-volatile register
- Override input forces all outputs to logic 0
- Internal non-volatile register write/readable via $\mathrm{I}^{2} \mathrm{C}$-bus
- Write-protect pin enables/disables $\mathrm{I}^{2} \mathrm{C}$ writes to register
- 2.5 V multiplexed outputs
- 3.3 V non-multiplexed output (latched)
- 5 V tolerant inputs
- Useful for 'jumperless’ configuration of PC motherboards
- Designed for use in Pentium Pro/Pentium II ${ }^{T M}$ systems


## DESCRIPTION

The primary function of the 4 -bit 2 -to- $1 \mathrm{I}^{2} \mathrm{C}$ multiplexer is to select either a 4 -bit input or data from a non-volatile register and drive this value onto the output pins. One additional non-multiplexed register output is also provided. The non-multiplexed output is latched to prevent output value changes during $I^{2} \mathrm{C}$ writes to the non-volatile register. A write protect input is provided to enable/disable the ability to write to the non-volatile register. An "override" input feature forces all outputs to logic 0 .


## PIN CONFIGURATION



SW00579
Figure 1. Pin configuration

## ORDERING INFORMATION

| PACKAGES | TEMPERATURE RANGE | ORDER CODE | TOPSIDE MARK | DRAWING NUMBER |
| :---: | :---: | :---: | :---: | :---: |
| $16-$ Pin Plastic SO | 0 to $+70^{\circ} \mathrm{C}$ | PCA8550D | PCA8550 | SOT109-1 |
| 16 -Pin Plastic SSOP | 0 to $+70^{\circ} \mathrm{C}$ | PCA8550DB | PA8550 | SOT338-1 |
| $16-$ Pin Plastic TSSOP | 0 to $+70^{\circ} \mathrm{C}$ | PCA8550PW | PCA8550 | SOT403-1 |

Standard packing quantities and other packaging data is available at www.philipslogic.com/packaging.

## FUNCTIONAL DESCRIPTION

When the MUX_SELECT signal is logic 0 , the multiplexer will select the data from the non-volatile register to drive on the MUX_OUT pins. When the MUX_SELECT signal is logic 1, the multiplexer will select the MUX_IN lines to drive on the MUX_OUT pins. The MUX_SELECT signal is also used to latch the NON_MUXED_OUT signal which outputs data from the non-volatile register. The NON_MUXED_OUT signal latch is transparent when MUX_SELECT is in a logic 0 state, and will latch data when MUX_SELECT is in a logic 1 state. When the active-LOW OVERRIDE_N signal is set to logic 0 and the MUX_SELECT signal is at a logic 0 , all outputs will be driven to logic 0 . This information is summarized in Table 1.

The write protect (WP) input is used to control the ability to write the contents of the 5 -bit non-volatile register. If the WP signal is logic 0 , the $\mathrm{I}^{2} \mathrm{C}$-bus will be able to write the contents of the non-volatile register. If the WP signal is logic 1, data will not be allowed to be written into the non-volatile register.

The factory default for the contents of the non-volatile register are all logic 0 . These stored values can be read or written using the $I^{2} \mathrm{C}$ bus (described in the next section).
The OVERRIDE_N, WP, MUX_IN, and MUX_SELECT signals have internal pull-up resistors. See the DC and AC Characteristics for hysteresis and signal spike suppression figures.

## 4-bit multiplexed/1-bit latched 5-bit ${ }^{2}$ ² EEPROM DIP switch

## PIN DESCRIPTION

| $\begin{gathered} \text { PIN } \\ \text { NUMBER } \end{gathered}$ | SYMBOL | FUNCTION |
| :---: | :---: | :---: |
| 1 | $1^{2} \mathrm{C}$ SCL | ${ }^{12} \mathrm{C}$-bus clock |
| 2 | $1^{2} \mathrm{C}$ SDA | Bi-directional $\mathrm{I}^{2} \mathrm{C}$-bus data |
| 3 | OVERRIDE_N | Forces all outputs to logic 0 |
| 4 | MUX_IN A | External inputs to multiplexer |
| 5 | MUX_IN B |  |
| 6 | MUX_IN C |  |
| 7 | MUX_IN D |  |
| 8 | GND | Common ground voltage rail |
| 9 | MUX_OUT D | 2.5 V multiplexed output |
| 10 | MUX_OUT C |  |
| 11 | MUX_OUT B |  |
| 12 | MUX_OUT A |  |
| 13 | MUX_SELECT | Selects MUX_IN inputs or register contents for MUX_OUT outputs |
| 14 | NON_MUXED_OUT | TTL-level output from non-volatile memory |
| 15 | WP | Non-volatile register write-protect |
| 16 | $\mathrm{V}_{C C}$ | Positive voltage rail |

## FUNCTION TABLE

Table 1. Function table

| OVERRIDE <br> _N | MUX_SELECT | MUX_OUT <br> OUTPUTS | NON_MUXED_OUT <br> OUTPUT |
| :---: | :---: | :---: | :---: |
| 0 | 0 | All 0's | All O's |
| 0 | 0 | MUX_IN <br> inputs | Latched <br> NON_MUXED_OUT |
| 1 | 1 | From non- <br> volatile <br> register | From non-volatile <br> register |
| 1 | MUX_IN <br> inputs | From non-volatile <br> register |  |

## NOTE

1. Latched NON MIXED OUT state will be the value present on the NON_MUXED_OUT output at the time of the MUX_SELECT input transitioned from a logic 0 to a logic 1 state.

## $\mathbf{I}^{2} \mathrm{C}$ INTERFACE

Communicating with this device is initiated by sending a valid address on the $\mathrm{I}^{2} \mathrm{C}$-bus. The address format (see Flgure 2) is a fixed unique 7 -bit value followed by a 1 -bit read/write value which determines the direction of the data transfer.


Figure 2. $\mathrm{I}^{2} \mathrm{C}$ Address Byte
Following the address and acknowledge bit are 8 data bits which, depending on the read/write bit in the address, will read data from or write data to the non-volatile register. Data will be written to the register if the read/write bit is logic 0 and the WP input is logic 0 . Data will be read from the register if the bit is logic 1 . The three high-order bits (see Flgure 3) are logic 0 . The next bit is data which is non-multiplexed. The low four bits are the data which will be multiplexed. A write with any of the first three bits non-zero will be aborted.

## NOTE:

1. To ensure data integrity, the non-volatile register must be internally write protected when $\mathrm{V}_{\mathrm{CC}}$ to the $\mathrm{I}^{2} \mathrm{C}$-bus is powered down or $\mathrm{V}_{\mathrm{CC}}$ to the component is dropped below normal operating levels.


Figure 3. $I^{2} \mathrm{C}$ Data Byte

## POWER-ON RESET (POR)

When power is applied to $\mathrm{V}_{\mathrm{CC}}$, an internal power-on reset holds the PCA8550 in a reset state until $\mathrm{V}_{\mathrm{CC}}$ has reached $\mathrm{V}_{\text {POR }}$. At that point, the reset condition is released and the PCA8550 volatile registers and ${ }^{2} \mathrm{C}$ state machine will initialize to their default states.
The MUX_OUT and NON_MUXED_OUT pin values depend on:

- the OVERRIDE_N and MUX_SELECT logic levels
- the previously stored values in the EEPROM register/current MUX_IN pin values as shown in Table 1.

BLOCK DIAGRAM


Figure 4. Block diagram

## 4-bit multiplexed/1-bit latched 5-bit ${ }^{2}$ ² EEPROM DIP switch

## ABSOLUTE MAXIMUM RATINGS ${ }^{1,2}$

In accordance with the Absolute Maximum Rating System (IEC 134)
Voltages are referenced to GND (ground $=0 \mathrm{~V}$ )

| SYMBOL | PARAMETER | CONDITIONS | RATING | UNIT |
| :---: | :--- | :--- | :---: | :---: |
| $\mathrm{V}_{\mathrm{CC}}$ | DC supply voltage |  | -0.5 to +4.6 | V |
| $\mathrm{~V}_{\mathrm{I}}$ | DC input voltage | Note 3 | -1.5 to $\mathrm{V}_{\mathrm{CC}}+1.5$ | V |
| $\mathrm{~V}_{\text {OUT }}$ | DC output voltage | Note 3 | -0.5 to $\mathrm{V}_{\mathrm{CC}}+0.5$ | V |
| $\mathrm{~T}_{\text {stg }}$ | Storage temperature range |  | -60 to +150 | ${ }^{\circ} \mathrm{C}$ |

## NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed $150^{\circ} \mathrm{C}$.
3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

## RECOMMENDED OPERATING CONDITIONS

| SYMBOL | PARAMETER |  | CONDITIONS | LIMITS |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | MAX |  |
| $\mathrm{V}_{\mathrm{CC}}$ | DC supply voltage |  |  |  | 3.0 | 3.6 | V |
| $\mathrm{V}_{\mathrm{POR}}$ | Power-on reset voltage |  | No load; $\mathrm{V}_{\mathrm{I}}=\mathrm{V}_{\mathrm{DD}}$ or GND | - | 2.6 | V |
| $\mathrm{V}_{\text {IL }}$ | LOW-level input voltage | SCL, SDA | $\mathrm{l}_{\mathrm{OL}}=3 \mathrm{~mA}$ | -0.5 | 0.9 | V |
| $\mathrm{V}_{\mathrm{IH}}$ | HIGH-level input voltage | SCL, SDA | $\mathrm{l}_{\mathrm{OL}}=3 \mathrm{~mA}$ | 2.7 | 4.0 | V |
| $\mathrm{V}_{\mathrm{OL}}$ | LOW-level output voltage | SCL, SDA | $\mathrm{l}_{\mathrm{OL}}=3 \mathrm{~mA}$ | - | 0.4 | V |
| VIL | LOW-level input voltage | OVERRIDE_N, MUX IN, MUX_SĒLECT |  | -0.5 | 0.8 | V |
| $\mathrm{V}_{\mathrm{IH}}$ | HIGH-level input voltage | OVERRIDE_N, MUX IN, MUX_SELECT |  | 2.0 | 4.0 | V |
| IOL | LOW-level output current | MUX_OUT NON_MUXED_OUT |  | - | 2.0 | mA |
| ${ }^{\text {IOH }}$ | HIGH-level output current | MUX_OUT <br> NON_MUXED_OUT |  | - | -2.0 | mA |
| dt/dv | Input transition rise or fall time |  |  | 0 | 10 | ns/V |
| $\mathrm{T}_{\text {amb }}$ | Operating ambient temperature |  |  | 0 | 70 | ${ }^{\circ} \mathrm{C}$ |

## 4-bit multiplexed/1-bit latched 5-bit ${ }^{2}{ }^{2} \mathrm{C}$ EEPROM DIP switch

DC CHARACTERISTICS
Temp $=0$ to $+70^{\circ} \mathrm{C} 3.0 \mathrm{~V}<\mathrm{V}_{\mathrm{CC}} \leq 3.6 \mathrm{~V}$

| SYMBOL | PARAMETER | CONDITIONS | LIMITS |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | MAX |  |
| SCL, SDA |  |  |  |  |  |
| $\mathrm{V}_{\text {OL }}$ | LOW-level output voltage |  | 0 | 0.6 | V |
| loL | LOW-level output current | $\mathrm{V}_{\mathrm{OL}}=0.4 \mathrm{~V}$ |  | 3.0 | mA |
| $\mathrm{l}_{\mathrm{OL}}$ | LOW-level output current | $\mathrm{V}_{\mathrm{OL}}=0.6 \mathrm{~V}$ |  | 6.0 | mA |
| $\mathrm{ILL}^{1}$ | LOW-level input current | $\mathrm{V}_{\text {IL }}=0.4 \mathrm{~V}$ | -7 | -32 | $\mu \mathrm{A}$ |
| $\mathrm{IIH}^{\text {H }}$ | HIGH-level input current | $\mathrm{V}_{\mathrm{IH}}=2.4 \mathrm{~V}$ | -1.5 | -12 | $\mu \mathrm{A}$ |
| $\mathrm{V}_{\text {hys }}$ | Hysteresis voltage |  | 0.19 |  | V |
| OVERRIDE_N, WP, MUX_SELECT |  |  |  |  |  |
| 1 IL | LOW-level input current |  | -86 | -267 | $\mu \mathrm{A}$ |
| IIH | HIGH-level input current |  | -20 | -100 | $\mu \mathrm{A}$ |
| MUX_IN A $\Rightarrow$ D |  |  |  |  |  |
| $1 / \mathrm{L}$ | LOW-level input current | $\mathrm{V}_{\mathrm{IL}}=0.4 \mathrm{~V}$ | -0.72 | -2.0 | mA |
| $\mathrm{IIH}^{\text {H }}$ | HIGH-level input current | $\mathrm{V}_{1 \mathrm{H}}=2.4 \mathrm{~V}$ | -0.72 | -2.0 | mA |
| MUX_OUT |  |  |  |  |  |
| $\mathrm{V}_{\text {OL }}$ | LOW-level output voltage | $\mathrm{l} \mathrm{OL}=100 \mu \mathrm{~A}$ | -0.3 | 0.4 | V |
|  |  | $\mathrm{l} \mathrm{OL}=2.0 \mathrm{~mA}$ | -0.3 | 0.7 |  |
| $\mathrm{V}_{\mathrm{OH}}$ | HIGH-level output voltage | $\mathrm{I}_{\mathrm{OH}}=-100 \mu \mathrm{~A}$ | 2.0 | 2.625 | V |
|  |  | $\mathrm{I}_{\mathrm{OH}}=-1.0 \mathrm{~mA}$ | 1.7 | 2.625 |  |
| NON_MUXED_OUT |  |  |  |  |  |
| $\mathrm{V}_{\text {OL }}$ | LOW-level output voltage | l OL $=100 \mu \mathrm{~A}$ | -0.5 | 0.4 | V |
|  |  | $\mathrm{l}_{\mathrm{OL}}=2.0 \mathrm{~mA}$ | -0.5 | 0.7 |  |
| $\mathrm{V}_{\mathrm{OH}}$ | HIGH-level output voltage | $\mathrm{l}_{\mathrm{OH}}=-100 \mu \mathrm{~A}$ | 2.4 | 3.6 | V |
|  |  | $\mathrm{l}_{\mathrm{OH}}=-2.0 \mathrm{~mA}$ | 2.0 | 3.6 |  |
| ICC | Quiescent supply current | $\mathrm{V}_{\mathrm{CC}}=3.3 \mathrm{~V}$; $\mathrm{V}_{\mathrm{I}}=0 \mathrm{~V}$ to $\mathrm{V}_{\mathrm{CC}}$ |  | 10 | mA |
| $\mathrm{I}_{\mathrm{CC}}$ | Quiescent supply current | $\mathrm{V}_{\mathrm{I}}=\mathrm{V}_{\mathrm{CC}}$ |  | 500 | $\mu \mathrm{A}$ |
| $\mathrm{Cl}_{1}$ | Input capacitance |  |  | 10 | pF |
|  | ESD protection |  | 2.0 |  | KV |
|  | Input diode clamp voltage |  | -1.5 |  | V |

## NOTES:

1. $\mathrm{V}_{\mathrm{HYS}}$ is the hysteresis of Schmitt-Trigger inputs
2. Human body model

## NON-VOLATILE STORAGE SPECIFICATIONS

| Parameter | Specification |
| :---: | :---: |
| Memory cell data retention | 10 years min |
| Number of memory cell write cycles | 100,000 cycles min |

Application Note AN250 I $I^{2} C$ DIP Switch provides additional information on memory cell data retention and the minimum number of write cycles.

## 4-bit multiplexed/1-bit latched 5-bit ${ }^{2}{ }^{2} \mathrm{C}$ EEPROM DIP switch

## AC CHARACTERISTICS

| SYMBOL | PARAMETER | LIMITS |  | UNIT |
| :---: | :---: | :---: | :---: | :---: |
|  |  | MIN | MAX |  |
| $\mathrm{t}_{\text {MPD }}$ | Mux input to output propagation delay |  | 20.0 | ns |
| tsov | MUX_SELECT to output valid |  | 22 | ns |
| tovn | OVERRIDE_N to NON_MUX output delay |  | 15.0 | ns |
| tovm | OVERRIDE_N to mux output delay |  | 25.0 | ns |
| $\mathrm{t}_{\mathrm{R}}$ | Output rise time | 1.0 | 3.0 | $\mathrm{ns} / \mathrm{V}$ |
| $\mathrm{t}_{\mathrm{F}}$ | Output fall time | 1.0 | 3.0 | ns/V |
| $\mathrm{C}_{\mathrm{L}}$ | Test load capacitance on Muxed/Non-Muxed outputs |  | 15 | pF |
| ${ }^{12} \mathrm{C}$-bus |  |  |  |  |
| $\mathrm{f}_{\mathrm{SCL}}$ | $1^{2} \mathrm{C}$ clock frequency | 10 | 400 | KHz |
| $\mathrm{t}_{\mathrm{SCH}}$ | $1^{2} \mathrm{C}$ clock HIGH time | 600 |  | ns |
| ${ }_{\text {t }}^{\text {SCL }}$ | $\mathrm{I}^{2} \mathrm{C}$ clock LOW time | 1.3 |  | ns |
| $\mathrm{t}_{\text {DSP }}$ | ${ }^{1} 2 \mathrm{C}$ data spike time | 0 | 50 | ns |
| $t_{\text {SDS }}$ | $1^{2} \mathrm{C}$ data set-up time | 100 |  | ns |
| $\mathrm{t}_{\text {SDH }}$ | $1^{2} \mathrm{C}$ data hold time | 0 |  | ns |
| $\mathrm{t}_{\mathrm{ICR}}$ | $1^{2} \mathrm{C}$ input rise time ( $10-400 \mathrm{pF}$ bus) | 20 | 300 | ns |
| $\mathrm{t}_{\text {ICF }}$ | ${ }^{2} \mathrm{C}$ input fall time ( $10-400 \mathrm{pF}$ bus) | 20 | 300 | ns |
| $\mathrm{t}_{\text {BUF }}$ | $1^{2} \mathrm{C}$-bus free time between start and stop | 1.3 |  | ns |
| $\mathrm{t}_{\text {STS }}$ | ${ }^{2} \mathrm{C}$ repeated start condition set-up | 600 |  | ns |
| $\mathrm{t}_{\text {STH }}$ | ${ }^{2} \mathrm{C}$ repeated start condition hold | 600 |  | ns |
| tsps | $1^{2} \mathrm{C}$ stop condition set-up | 600 |  | ns |
| $\mathrm{C}_{\mathrm{B}}$ | $1^{2} \mathrm{C}$-bus capacitive load |  | 400 | pF |
| $\mathrm{T}_{\mathrm{W}}$ | Write cycle time ${ }^{1}$ |  |  | ms |

## NOTE:

1. WRITE CYCLE time can only be measured indirectly during write cycle. The device will not acknowledge its $\mathrm{I}^{2} \mathrm{C}$ address.

## 4-bit multiplexed/1-bit latched 5-bit

 $I^{2} \mathrm{C}$ EEPROM DIP switch

DIMENSIONS (inch dimensions are derived from the original mm dimensions)

| UNIT | $\begin{gathered} \mathrm{A} \\ \max . \end{gathered}$ | $\mathrm{A}_{1}$ | $\mathrm{A}_{2}$ | $\mathrm{A}_{3}$ | $b_{p}$ | c | $\mathrm{D}^{(1)}$ | $E^{(1)}$ | e | $\mathrm{H}_{\mathrm{E}}$ | L | $L_{p}$ | Q | v | w | y | $Z^{(1)}$ | $\theta$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| mm | 1.75 | $\begin{aligned} & 0.25 \\ & 0.10 \end{aligned}$ | $\begin{aligned} & 1.45 \\ & 1.25 \end{aligned}$ | 0.25 | $\begin{aligned} & 0.49 \\ & 0.36 \end{aligned}$ | $\begin{aligned} & 0.25 \\ & 0.19 \end{aligned}$ | $\begin{gathered} 10.0 \\ 9.8 \end{gathered}$ | $\begin{aligned} & 4.0 \\ & 3.8 \end{aligned}$ | 1.27 | $\begin{aligned} & 6.2 \\ & 5.8 \end{aligned}$ | 1.05 | $\begin{aligned} & 1.0 \\ & 0.4 \end{aligned}$ | $\begin{aligned} & 0.7 \\ & 0.6 \end{aligned}$ | 0.25 | 0.25 | 0.1 | 0.7 0.3 | $\begin{aligned} & 8^{0} \\ & 0^{\circ} \end{aligned}$ |
| inches | 0.069 | $\begin{aligned} & 0.010 \\ & 0.004 \end{aligned}$ | $\begin{aligned} & 0.057 \\ & 0.049 \end{aligned}$ | 0.01 | $\begin{aligned} & 0.019 \\ & 0.014 \end{aligned}$ | $\left\|\begin{array}{\|c\|} 0.0100 \\ 0.0075 \end{array}\right\|$ | $\begin{aligned} & 0.39 \\ & 0.38 \end{aligned}$ | $\begin{aligned} & 0.16 \\ & 0.15 \end{aligned}$ | 0.050 | $\begin{aligned} & 0.244 \\ & 0.228 \end{aligned}$ | 0.041 | $\begin{aligned} & 0.039 \\ & 0.016 \end{aligned}$ | $\begin{aligned} & 0.028 \\ & 0.020 \end{aligned}$ | 0.01 | 0.01 | 0.004 | $\begin{aligned} & 0.028 \\ & 0.012 \end{aligned}$ |  |

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES |  |  | EUROPEAN PROJECTION | ISSUE DATE |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | IEC | JEDEC | EIAJ |  |  |
| SOT109-1 | 076E07 | MS-012 |  | - (¢) | $\begin{aligned} & -97-05-22 \\ & 99-12-27 \end{aligned}$ |



DIMENSIONS (mm are the original dimensions)

| UNIT | $\mathbf{A}$ <br> $\mathbf{m a x}$. | $\mathbf{A}_{\mathbf{1}}$ | $\mathbf{A}_{\mathbf{2}}$ | $\mathbf{A}_{\mathbf{3}}$ | $\mathbf{b}_{\mathbf{p}}$ | $\mathbf{c}$ | $\mathbf{D}^{(1)}$ | $\mathbf{E}^{(1)}$ | $\mathbf{e}$ | $\mathbf{H}_{\mathbf{E}}$ | $\mathbf{L}$ | $\mathbf{L}_{\mathbf{p}}$ | $\mathbf{Q}$ | $\mathbf{v}$ | $\mathbf{w}$ | $\mathbf{y}$ | $\mathbf{Z}^{(1)}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| mm | 2.0 | 0.21 | 1.80 | 0.05 | 1.65 | 0.25 | 0.38 | 0.20 | 6.4 | 5.4 | 0.6 | 7.9 | 1.25 | 1.03 | 0.9 | 0.2 | 0.13 |

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES |  |  | EUROPEAN PROJECTION | ISSUE DATE |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | IEC | JEDEC | EIAJ |  |  |
| SOT338-1 |  | MO-150 |  | $\square$ ( | $\begin{aligned} & 95-02-04 \\ & 99-12-27 \end{aligned}$ |



DIMENSIONS (mm are the original dimensions)

| UNIT | A max. | $\mathrm{A}_{1}$ | $\mathrm{A}_{2}$ | $\mathrm{A}_{3}$ | $\mathrm{b}_{\mathrm{p}}$ | c | $\mathrm{D}^{(1)}$ | $E^{(2)}$ | e | $\mathrm{H}_{\mathrm{E}}$ | L | $L_{p}$ | Q | v | w | y | $Z^{(1)}$ | $\theta$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| mm | 1.10 | $\begin{aligned} & 0.15 \\ & 0.05 \end{aligned}$ | $\begin{aligned} & 0.95 \\ & 0.80 \end{aligned}$ | 0.25 | $\begin{aligned} & 0.30 \\ & 0.19 \end{aligned}$ | $\begin{aligned} & 0.2 \\ & 0.1 \end{aligned}$ | $5.1$ | $\begin{aligned} & 4.5 \\ & 4.3 \end{aligned}$ | 0.65 | $\begin{aligned} & 6.6 \\ & 6.2 \end{aligned}$ | 1.0 | $\begin{aligned} & 0.75 \\ & 0.50 \end{aligned}$ | $\begin{aligned} & 0.4 \\ & 0.3 \end{aligned}$ | 0.2 | 0.13 | 0.1 | $\begin{aligned} & 0.40 \\ & 0.06 \end{aligned}$ | $8^{0}$ $0^{\circ}$ |

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES |  |  | EUROPEANPROJECTION | ISSUE DATE |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | IEC | JEDEC | EIAJ |  |  |
| SOT403-1 |  | MO-153 |  | $\square$ (号 | $\begin{aligned} & -95-04-04 \\ & 99-12-27 \end{aligned}$ |

## REVISION HISTORY

| Rev | Date | Description |
| :--- | :--- | :--- |
| -6 | 20030627 | Product data (9397 750 11678); ECN 853-2015 29936 dated 19 May 2003. <br> Supersedes data of 2001 Jan 12 (9397 750 07926). <br> Modifications: <br> $\bullet$ <br> $\bullet$ Update marketing information. |
| -5 | 20010112 | Increase number of write cycles from 3K to 100K. |

## 4-bit multiplexed/1-bit latched 5-bit ${ }^{2} \mathrm{C}$ EEPROM DIP switch



Purchase of Philips $\mathrm{I}^{2} \mathrm{C}$ components conveys a license under the Philips' $\mathrm{I}^{2} \mathrm{C}$ patent to use the components in the ${ }^{2} \mathrm{C}$ system provided the system conforms to the ${ }^{2}{ }^{2} \mathrm{C}$ specifications defined by Philips. This specification can be ordered using the code 939839340011.

## Data sheet status

| Level | Data sheet status ${ }^{[1]}$ | Product <br> status ${ }^{[2]}$ [3] | Definitions |
| :--- | :--- | :--- | :--- |
| I | Objective data | Development | This data sheet contains data from the objective specification for product development. <br> Philips Semiconductors reserves the right to change the specification in any manner without notice. |
| II | Preliminary data | Qualification | This data sheet contains data from the preliminary specification. Supplementary data will be published <br> at a later date. Philips Semiconductors reserves the right to change the specification without notice, in <br> order to improve the design and supply the best possible product. |
| III | Product data | Production | This data sheet contains data from the product specification. Philips Semiconductors reserves the <br> right to make changes at any time in order to improve the design, manufacturing and supply. Relevant <br> changes will be communicated via a Customer Product/Process Change Notification (CPCN). |

[1] Please consult the most recently issued data sheet before initiating or completing a design.
[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

## Definitions

Short-form specification - The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information - Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

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